

Diagonal 11.1 mm (Type 2/3) CMOS solid-state Image Sensor with Square Pixel for Monochrome Cameras

Description

The IMX566-AAMJ is a diagonal 11.1 mm (Type 2/3) CMOS active pixel type solid-state image sensor with a square pixel array and 8.13 M effective pixels. This chip features a global shutter with variable charge-integration time. This chip operates with analog 3.3 V, 2.9 V, digital 1.1 V, and interface 1.8 V quadruple power supply. High sensitivity and low dark current characteristics are achieved.

(Applications: FA cameras, ITS cameras)

Features

- ◆ CMOS active pixel type dots
- ◆ Built-in timing adjustment circuit, H/V driver and serial communication circuit
- ◆ Global shutter function
- ◆ Input frequency 37.125 MHz / 74.25 MHz / 54 MHz
- ◆ Number of recommended recording pixels: 2840 (H) × 2840 (V) approx. 8.06 M pixels
- ◆ Readout mode
 - All-pixel scan mode
 - Vertical / Horizontal 1/2 Subsampling mode
 - 2 × 2 FD binning mode
 - ROI mode
 - Vertical / Horizontal - Normal / Inverted readout mode
- ◆ Readout rate
 - Maximum frame rate in
 - All-pixel scan mode: 8 bit 62.6 frame/s, 10 bit 51.3 frame/s, 12 bit 43.4 frame/s
- ◆ Pulse Output Function
 - The monitor output for Exposure period
 - Programmable pulse output
- ◆ 8-bit / 10-bit / 12-bit A/D converter
- ◆ CDS / PGA function
 - 0 dB to 24 dB: Analog Gain (0.1 dB step)
 - 24.1 dB to 48 dB: Analog Gain: 24 dB + Digital Gain: 0.1 dB to 24 dB (0.1 dB step)
- ◆ I/O interface
 - CSI-2 serial data output (2 Lane / 4 Lane) (1188 / 891 / 594 Mbps per ch)
- ◆ Recommended lens F number: 2.8 or more (Close side)

Pregius S

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Device Structure

◆ CMOS image sensor		
◆ Image size	Diagonal 11.1 mm (Type 2/3)	Approx. 8.13 M pixels
◆ Total number of pixels	2856 (H) × 2912 (V)	Approx. 8.31 M pixels
◆ Number of effective pixels	2856 (H) × 2848 (V)	Approx. 8.13 M pixels
◆ Number of active pixels	2856 (H) × 2848 (V)	Approx. 8.13 M pixels
◆ Number of recommended recording pixels	2840 (H) × 2840 (V)	Approx. 8.06 M pixels
◆ Unit cell size	2.74 μm (H) × 2.74 μm (V)	
◆ Optical black	Horizontal (H) direction: Front 0 pixel, rear 0 pixel Vertical (V) direction: Front 64 pixels, rear 0 pixel	
◆ Package	230 pin LGA	20.0 mm (H) × 16.8 mm (V)

Image Sensor Characteristics

(T_j = 60 °C)

Item		Value	Remarks
Sensitivity	Typ.	14510 Digit/lx/s	
Saturation signal	Min.	4094 Digit	

Basic Drive Mode

Drive mode	Recommended number of recording pixels	Maximum frame rate [frame/s]	Output interface	ADC [bit]
All pixel	2840 (H) × 2840 (V) approx. 8.06 M pixels	62	CSI-2	8
		51	CSI-2	10
		43	CSI-2	12
Vertical / Horizontal 1/2 subsampling	1420 (H) × 1420 (V) approx. 2.01 M pixels	214	CSI-2	8
		180	CSI-2	10
		155	CSI-2	12
2 × 2 FD binning mode	1420 (H) × 1420 (V) approx. 2.01 M pixels	214	CSI-2	8
		180	CSI-2	10
		155	CSI-2	12

